

R6046FNZ1

Nch 600V 46A Power MOSFET

V_{DSS}	600V
R _{DS(on)} (Max.)	0.098Ω
I _D	46A
P_D	694W

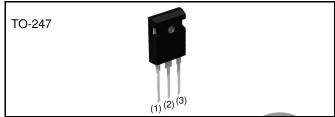
Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Gate-source voltage (V_{GSS}) guaranteed to be $\pm 30V$.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.
- 6) Pb-free lead plating; RoHS compliant

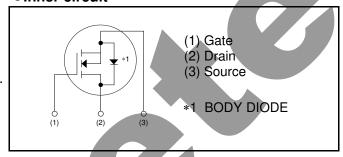
Application

Switching Power Supply

Outline



●Inner circuit



Packaging specifications

Packaging	Tube
Reel size (mm)	-
Tape width (mm)	-
Basic ordering unit (pcs)	450
Taping code	C9
Marking	R6046FNZ1
	Reel size (mm) Tape width (mm) Basic ordering unit (pcs) Taping code

● Absolute maximum ratings(T_a = 25°C)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	600	V
Continuous drain current $T_c = 25^{\circ}C$	I _D *1	±46	А
T _c = 100° C	I _D *1	±23	А
Pulsed drain current	I _{D,pulse} *2	±115	А
Gate - Source voltage	V_{GSS}	±30	V
Avalanche energy, single pulse	E _{AS} *3	142	mJ
Avalanche energy, repetitive	E _{AR} *4	5.4	mJ
Avalanche current	I _{AR} *3	23	Α
Power dissipation (T _c = 25°C)	P_{D}	694	W
Junction temperature	T _j	150	°C
Range of storage temperature	T_{stg}	-55 to +150	°C
Reverse diode dv/dt	dv/dt *5	15	V/ns

Absolute maximum ratings

Parameter	Symbol	Conditions	Values	Unit
Drain - Source voltage slope	dv/dt	$V_{DS} = 480V, I_{D} = 46A$ $T_{j} = 125^{\circ}C$	50	V/ns

●Thermal resistance

Parameter	Symbol	Values			Unit
r arameter	Symbol	Min.	Тур.	Max.	Offit
Thermal resistance, junction - case	R_{thJC}	-	-	0.18	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	1	30	°C/W
Soldering temperature, wavesoldering for 10s	T_{sold}		1	265	°C

$\bullet \textbf{Electrical characteristics}(T_a = 25^{\circ}C)$

Parameter	Symbol Conditions		Values			Unit
r arameter	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	600	-	-	V
Drain - Source avalanche breakdown voltage	V _{(BR)DS}	$V_{GS} = 0V, I_{D} = 46A$	-	700	1	V
		$V_{DS} = 600 V, V_{GS} = 0 V$				μΑ
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	1	100	μΑ
		T _j = 125°C	-	-	100	mA
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, \ V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3	1	5	V
		$V_{GS} = 10V, I_D = 23A$				
Static drain - source on - state resistance	R _{DS(on)} *6	T _j = 25°C	-	0.075	0.098	Ω
		T _j = 125°C	-	0.16	-	
Gate input resistance	R_{G}	f = 1MHz, open drain	-	1.7	-	Ω

• Electrical characteristics ($T_a = 25$ °C)

Parameter	Cumbal	Conditions	Values			Unit
r arameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Transconductance	g _{fs} *6	$V_{DS} = 10V, I_D = 23A$	15	31	-	S
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	6230	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	4000	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	85	-	
Effective output capacitance, energy related	C _{o(er)}	V _{GS} = 0V	-	175		
Effective output capacitance, time related	$C_{o(tr)}$	$V_{DS} = 0V$ to $480V$	-	596		pF
Turn - on delay time	t _{d(on)} *6	$V_{DD} \simeq 300V, V_{GS} = 10V$		73	ı	
Rise time	t _r *6	I _D = 23A	-	120	ı	ne
Turn - off delay time	t _{d(off)} *6	$R_L = 13.0\Omega$		240	480	ns
Fall time	t _f *6	$R_G = 10\Omega$	-	68	136	

•Gate Charge characteristics($T_a = 25$ °C)

Parameter	Symbol Conditions		Values			Unit
r arameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Qg *6	V _{DD} ≈ 300V	ı	150	ı	
Gate - Source charge	Q _{gs} *6	I _D = 46A	-	40	-	nC
Gate - Drain charge	Q _{gd} *6	$V_{GS} = 10V$	-	65	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300V$, $I_D = 46A$	-	7.1	-	V

^{*1} Limited only by maximum temperature allowed.

^{*2} $P_W \le 10 \mu s$, Duty cycle $\le 1\%$

^{*3} L \simeq 500 μ H, V_{DD} = 50V, R_G = 25 Ω , starting T_j = 25°C

^{*4} L $^{\sim}$ 500 μ H, V_{DD} = 50V, R_{G} = 25 Ω , starting T_{j} = 25°C, f = 10kHz

^{*5} Reference measurement circuits Fig.5-1.

^{*6} Pulsed

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ainietei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Inverse diode continuous, forward current	l _S *1	T _c = 25°C	ı	ı	46	А
Inverse diode direct current, pulsed	I _{SM} *2	1 c = 25 0	-	-	115	A
Forward voltage	V _{SD} *6	$V_{GS} = 0V, I_S = 46A$	-	-	1.5	V
Reverse recovery time	t _{rr} *6		-	145	-	ns
Reverse recovery charge	Q _{rr} *6	I _S = 46A di/dt = 100A/us	-	0.74	1-	μС
Peak reverse recovery current	I _{rrm} *6			9.6	-	Α
Peak rate of fall of reverse recovery current	di _{rr} /dt	T _j = 25°C		1200		A/μs

● Typical Transient Thermal Characteristics

Symbol	Value	Unit
R _{th1}	0.055	
R _{th2}	0.164	K/W
R _{th3}	0.821	

Symbol	Value	Unit
C _{th1}	0.0236	
C_{th2}	0.134	Ws/K
C_{th3}	1.09	

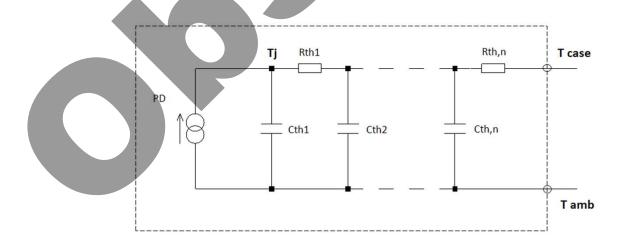


Fig.1 Power Dissipation Derating Curve

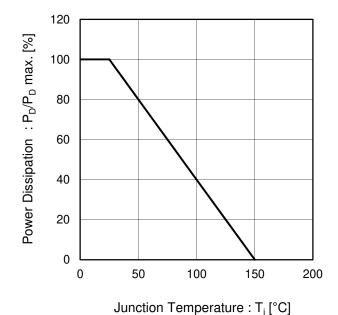
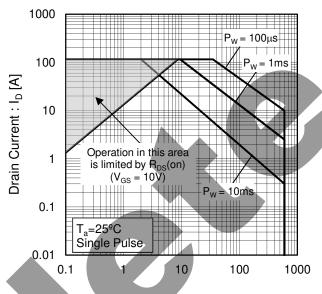
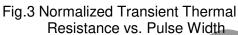


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]



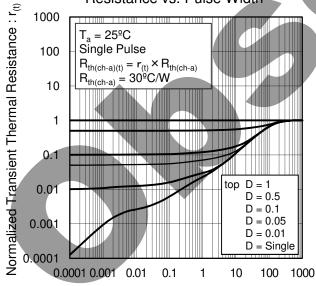


Fig.4 Avalanche Current vs Inductive Load

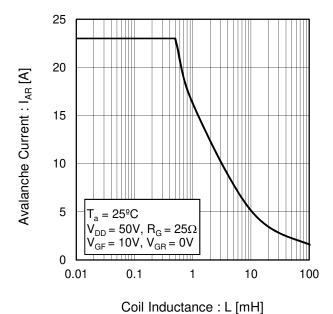
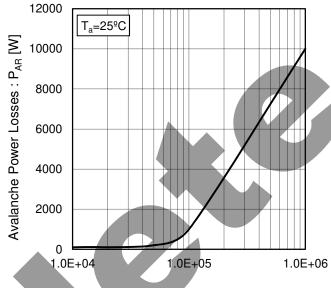
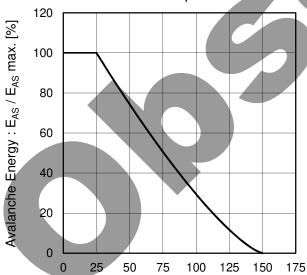


Fig.5 Avalanche Power Losses



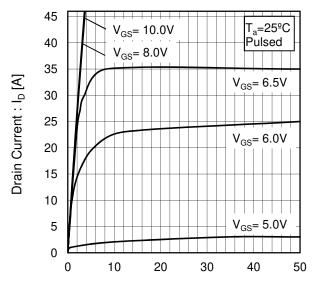
Frequency: f [Hz]

Fig.6 Avalanche Energy Derating Curve vs Junction Temperature



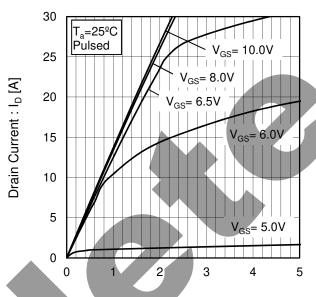
Junction Temperature : T_j [${}^{\circ}C$]

Fig.7 Typical Output Characteristics(I)



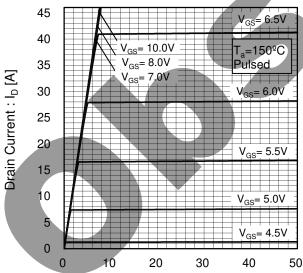
Drain - Source Voltage : V_{DS} [V]

Fig.8 Typical Output Characteristics(II)



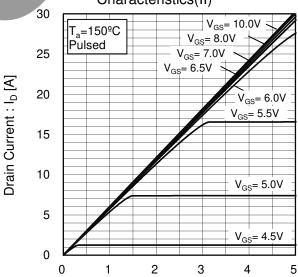
Drain - Source Voltage : V_{DS} [V]

Fig.9 $T_j = 150^{\circ}C$ Typical Output Characteristics(I)



Drain - Source Voltage: V_{DS} [V]

Fig.10 $T_j = 150$ °C Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

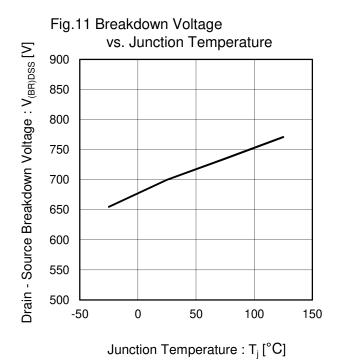


Fig.12 Typical Transfer Characteristics

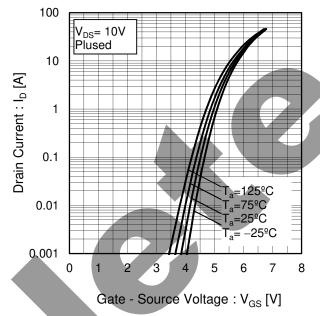


Fig.13 Gate Threshold Voltage vs. Junction Temperature

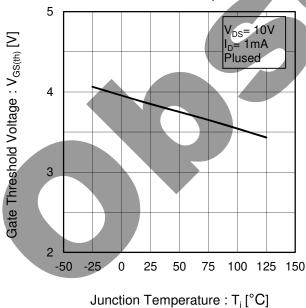


Fig.14 Transconductance vs. Drain Current

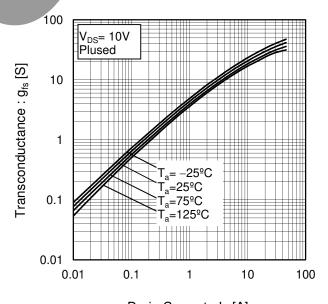
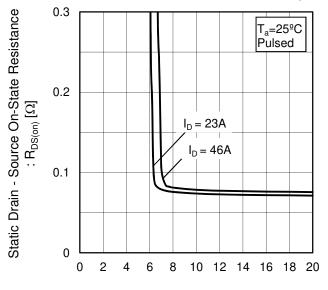
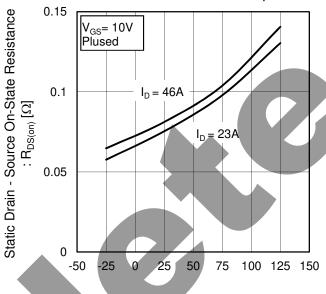


Fig.15 Static Drain - Source On - State Resistance vs. Gate Source Voltage



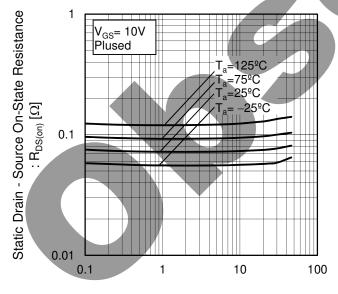
Gate - Source Voltage : V_{GS} [V]

Fig.16 Static Drain - Source On - State Resistance vs. Junction Temperature



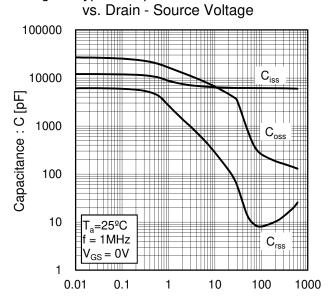
Junction Temperature : T_i [ºC]

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current



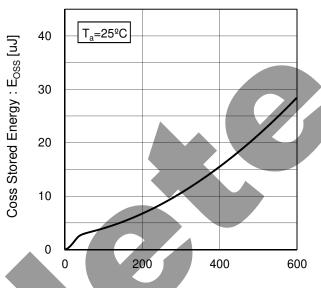
Drain Current: I_D [A]

Fig.18 Typical Capacitance



Drain - Source Voltage : $V_{DS}[V]$

Fig.19 Coss Stored Energy



Drain - Source Voltage : V_{DS} [V]

Fig.20 Switching Characteristics

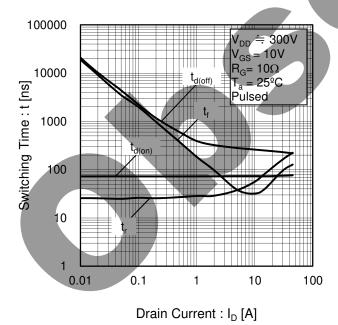
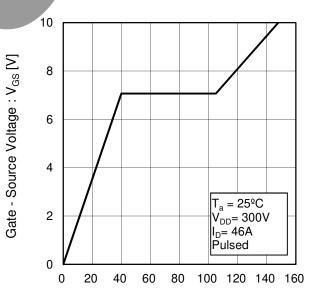
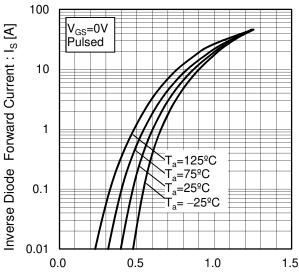


Fig.21 Dynamic Input Characteristics



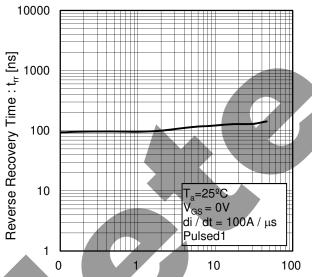
Total Gate Charge : Q_g [nC]

Fig.22 Inverse Diode Forward Current vs. Source - Drain Voltage



Source - Drain Voltage : V_{SD} [V]

Fig.23 Reverse Recovery Time vs.Inverse Diode Forward Current



Inverse Diode Forward Current : I_S [A]



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

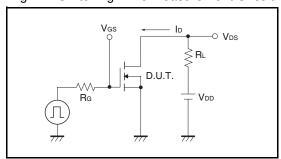


Fig.2-1 Gate Charge Measurement Circuit

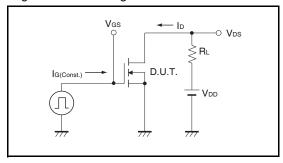


Fig.3-1 Avalanche Measurement Circuit

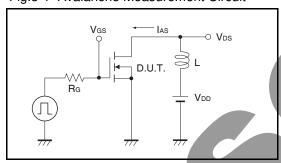


Fig.4-1 dv/dt Measurement Circuit

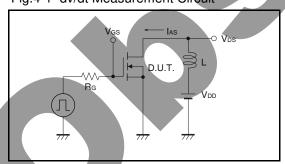


Fig.5-1 di/dt Measurement Circuit

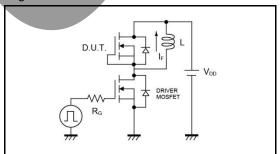


Fig.1-2 Switching Waveforms

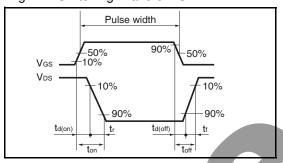


Fig.2-2 Gate Charge Waveform

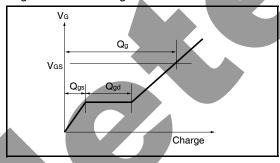


Fig.3-2 Avalanche Waveform

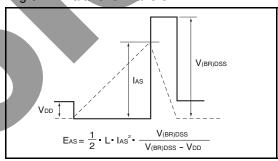


Fig.4-2 dv/dt Waveform

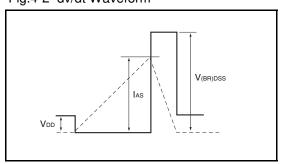
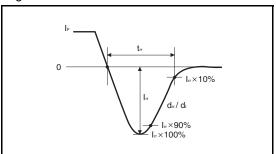
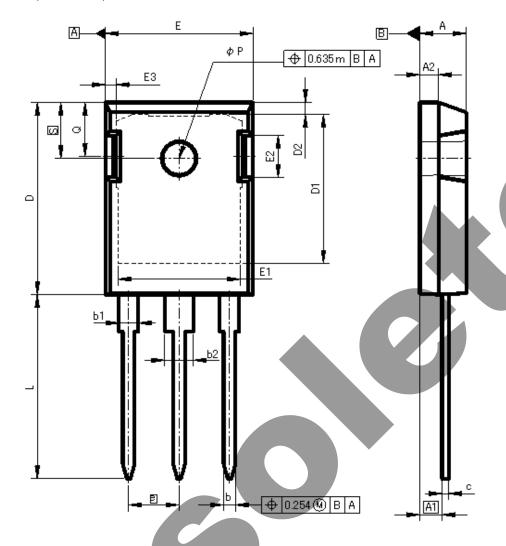


Fig.5-2 di/dt Waveform



● **Dimensions** (Unit: mm)

TO-247



DIM	MILIM	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.29	2.54	0.090	0.100
A2	1.91	2.16	0.075	0.085
b	1.14	1.40	0.045	0.055
b1	1.91	2.20	0.075	0.087
b2	2.92	3.20	0.115	0.126
C	0.61	0.80	0.024	0.031
D	20.80	21.34	0.819	0.840
D1	17.43	17.83	0.686	0.702
E	15.75	16.13	0.620	0.635
е	5.45		0.2	15
N	3.00		3.0	00
L	19.81	20.57	0.780	0.810
L1	3.81	4.32	0.150	0.170
ФР	3.55	3.65	0.140	0.144
Q	5.59	6.20	0.220	0.244
S	6.	15	0.2	40

Dimension in mm / inches

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSII	CLASS II b	CLASSIII
CLASSIV		CLASSⅢ	

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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